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ABSTRACT

THERMAL MECHANICAL PLANARIZATION IN INTEGRATED CIRCUITS

A method and equipment [10,50] is provided for planarization of ILD layers on a semiconductor wafer [14]. The method includes providing an oven [12] having a wafer holder [26] therein, placing the semiconductor wafer [14] on the wafer holder [26], and simultaneously applying mechanical pressure and heat to the ILD layer on the semiconductor wafer [14] using a mechanical device [16,56].



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FIGURE 3